

# Advanced Micro Technology Co., Ltd. (AMT) Announces New Advanced IC Substrate Capabilities and Industry-Leading Quick-Turn Delivery

Suzhou, China — February 2026 — Advanced Micro Technology Co., Ltd. (AMT), a rapidly rising innovator in advanced IC substrate manufacturing, today announced significant expansions to its technology portfolio and production capacity, positioning the company as one of the fastest-moving new entrants in the high-end substrate market. With its Taicang base now fully ramped for high-volume manufacturing (HVM) and its Anji base progressing toward new product introduction (NPI) in the second half of 2026, AMT is accelerating its strategy to support global customers with advanced FC-BGA substrates, high-layer-count designs, and industry-leading quick-turn delivery.

Founded in 2022, AMT has rapidly built a strong technical and manufacturing foundation across the Yangtze River Delta—China’s most concentrated region for semiconductor talent, supply chain partners, and advanced packaging customers. The company’s two production sites, combined with a Suzhou engineering office, enable close collaboration with customers and fast response to design, process, and reliability requirements.

## High-End FC-BGA Capability for Next-Generation Computing and Networking

AMT’s core product portfolio includes FC-BGA substrates supporting 8–20+ layer structures, ABF materials, SAP processes, and fine-pitch features down to 8/12  $\mu\text{m}$  line/space, 50  $\mu\text{m}$  via diameter, and 100  $\mu\text{m}$  pad pitch. These capabilities target high-performance computing, AI accelerators, graphics processors, networking ASICs, and advanced consumer SoCs.

The company has already shipped engineering samples across a wide range of form factors—from 19  $\times$  19 mm to 100  $\times$  100 mm—including ultra-large 205 mm and 300 mm packages. Customer builds span 4- to 18-layer designs, with demonstrated copper thickness uniformity, dielectric control, and high-density interconnect performance validated through JEDEC and IPC reliability testing.

## Fastest Turnaround in Its Class: Hot-Lot Delivery in as Little as 32 Days

One of AMT’s strongest differentiators is its aggressive quick-turn manufacturing model. Leveraging advanced automation, integrated quality systems, and a tightly coordinated engineering workflow, the company offers:

- Hot-lot lead time:  $14 + N \times 3$  days
- Standard lead time:  $20 + N \times 5$  days

(Where  $N$  represents the number of buildup layers in the substrate structure.)

For example, a 6-2-6 FC-BGA substrate can be delivered in just 32 days for hot-lot builds.

This speed is enabled by vertically integrated process control—from ABF lamination and SAP plating to laser drilling, AOI, backend finishing, and electrical test—supported by Japanese, German, and Taiwanese equipment platforms capable of sub-10  $\mu\text{m}$  resolution and high-precision registration.

For customers navigating compressed development cycles in AI, HPC, and advanced networking, AMT's turnaround time offers a strategic advantage in accelerating design validation and early-stage product ramps.

### **Scaling Capacity to Meet Global Demand**

The company's Taicang facility, covering 45 acres, is now HVM-ready with an annual output capacity of 36 million ABF substrates and a revenue target exceeding ¥2 billion. The Anji base, spanning 127 acres, will add 144 million BT substrates per year once fully operational, supporting computing, storage, consumer, and automotive applications.

Together, these sites form a scalable manufacturing platform designed to support both high-mix engineering builds and large-volume production for global customers.

### **Advanced R&D: Glass Core, Power Delivery, and Co-Packaged Optics**

AMT is also investing heavily in next-generation substrate technologies, including:

- Glass core substrates with 70% of NPI development completed
- Embedded DTC and inductors for advanced power delivery
- Package-level voltage regulation (PLVR)
- Substrates for co-packaged optics, supporting silicon photonics, VCSEL, and micro-LED integration

With more than 75 patents granted or pending, the company is building a strong IP foundation for future substrate architectures.

### **Commitment to Quality and Reliability**

AMT operates ISO9001, ISO14001, and ISO45001 systems, with IATF16949 underway. Its laboratory supports JEDEC, AEC, and IPC-compliant reliability testing, including TCT, HAST, HTSL, CAF, impedance, and multi-reflow evaluations. Recent customer builds have demonstrated 100% pass rates at the substrate level.

**About Advanced Micro Technology Co., Ltd. (AMT)** Advanced Micro Technology Co., Ltd. is a high-end IC substrate manufacturer specializing in FC-BGA, BT substrates, and advanced packaging materials. With production bases in Taicang and Anji and an engineering office in Suzhou, the company delivers high-performance substrates with fast turnaround and strong engineering support for global semiconductor customers.

For more information, please visit [www.amt-meta.com](http://www.amt-meta.com).